## Y5V Dielectric, KGM Series

## **General Specifications**



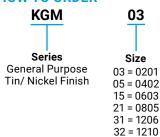


### **GENERAL DESCRIPTION**

Y5V formulations are for general-purpose use in a limited temperature range. They have a wide temperature characteristic of +22% −82% capacitance change over the operating temperature range of −30°C to +85°C.

These characteristics make Y5V ideal for decoupling applications within limited temperature range.

#### **HOW TO ORDER**







Voltage 0G = 4.0V0J = 6.3V1A = 10V 1C = 16V 1E = 25V1H = 50V

0J



2 Significant Digits +Number of zeros eg.  $10\mu F = 106$ 10nF = 103 47pF = 470

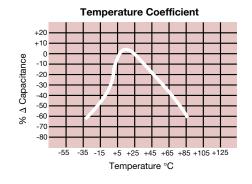


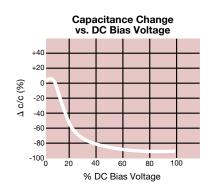


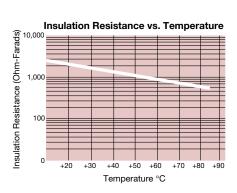


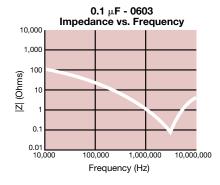
### **PACKAGING CODES**

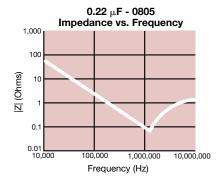
Code	EIA (inch)	IEC(mm)	7" Paper	7" Embossed	13" Paper	13"Embossed
03	0201	0603	Н		N	
05	0402	1005	Н		N	
15	0603	1608	Т		М	
21	0805	2012		U		L
31	1206	3216	Т	U	М	L
32	1210	3225		U		L

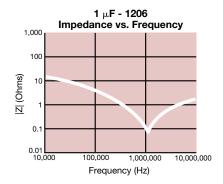












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Parame	ter/Test	Y5V Specification Limits	Measuring (	Conditions						
Operating Tem	perature Range	-30°C to +85°C	Temperature C	Temperature Cycle Chamber						
Capac	itance	Within specified tolerance	4							
Dissipati	on Factor	≤ 5.0% for ≥ 50V DC rating ≤ 7.0% for 25V DC rating ≤ 9.0% for 16V DC rating ≤ 12.5% for ≤ 10V DC rating	Freq.: 1.0 kHz ± 10% Voltage: 1.0Vrms ± .2V For Cap > 10 μF, 0.5Vrms @ 120Hz							
Insulation	Resistance	10,000MΩ or 500MΩ - $\mu$ F, whichever is less	Charge device with rated voltage for 120 ± 5 secs @ room temp/humidity							
Dielectric	Strength	No breakdown or visual defects	Charge device with 250% of rated voltage for 1-5 seconds, w/charge and discharge current limited to 50 mA (max)							
	Appearance	No defects	Deflectio	n: 2mm						
Resistance to	Capacitance Variation	≤ ±30%	Test Time: 3	0 seconds 1 mm/sec						
Flexure Stresses	Dissipation Factor	Meets Initial Values (As Above)	l v							
	Insulation Resistance	≥ Initial Value x 0.1	90 r	nm ———						
Solder	ability	≥ 95% of each terminal should be covered with fresh solder	Dip device in eutectic for 5.0 ± 0.5							
	Appearance	No defects, <25% leaching of either end terminal								
	Capacitance Variation	≤ ±20%								
Resistance to Solder Heat	Dissipation Factor	Meets Initial Values (As Above)	Dip device in eutectic solder at 260°C for 60 seconds. Store at room temperature for 24 ± 2 hours before measuring electrical properties.							
	Insulation Resistance	Meets Initial Values (As Above)	hours before measuring	g electrical properties.						
	Dielectric Strength	Meets Initial Values (As Above)		,						
	Appearance	No visual defects	Step 1: -30°C ± 2°	30 ± 3 minutes						
	Capacitance Variation	≤ ±20%	Step 2: Room Temp	≤ 3 minutes						
Thermal Shock	Dissipation Factor	Meets Initial Values (As Above)	Step 3: +85°C ± 2°	30 ± 3 minutes						
	Insulation Resistance	Meets Initial Values (As Above)	Step 4: Room Temp	≤ 3 minutes						
	Dielectric Strength	Meets Initial Values (As Above)	Repeat for 5 cycles and measure after 24 ±2 hours at room temperature							
	Appearance	No visual defects	-							
	Capacitance Variation	≤ ±30%	Charge device with twice rated voltage in test							
Load Life	Dissipation Factor	≤ Initial Value x 1.5 (See Above)	for 1000 hours (+48, -0)							
	Insulation Resistance	≥ Initial Value x 0.1 (See Above)	Remove from test chamb temperature for 24 ± 2 h							
	Dielectric Strength	Meets Initial Values (As Above)								
	Appearance	No visual defects	_							
	Capacitance Variation	≤ ±30%	Store in a test chamber s 5% relative humidi							
Load Humidity	Dissipation Factor	≤ Initial Value x 1.5 (See above)	(+48, -0) with rated	l voltage applied.						
. id.indity	Insulation Resistance	≥ Initial Value x 0.1 (See Above)	Remove from chamber temperature an 24 ± 2 hours bef	d humidity for						
	Dielectric Strength	Meets Initial Values (As Above)	27 ± 2 Hours ber	ore measuring.						

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SIZE		02	01		0402			06	03			00	05			12	06			10	210	
Soldering		Reflov		Dof	0.02	lovo	Reflow/ Wave				Reflow			Reflow/ Wave				Reflow/ Wave				
Packaging		All P		Reflow/ Wave All Paper		All Paper				per/ E			Paper/ Embossed				Paper/ Embossed					
		0.60							Pa		0.20	seu					<del></del>					
(L) Length	mm			1.00 ±0.10			1.60 ± 0.15				/			٥\	3.20± 0.20				3.20 ± 0.20			
	(in.)	(0.024±		(0.040±0.004)			(0.063 ± 0.006)				((	0.079 :		8)	(0.126 ± 0.008)				(0.126± 0.008)			3)
W) Width	mm	0.30		0.50 ±0.10		0.81 ±0.15		1.25 ±0.20 (0.049 ±0.008)				1.60±0.20 (0.063 ±0.008)				2.50±0.20 (0.098 ±0.008)			-\			
	(in.)	(0.011		/ (			(0.032 ±0.006)			((			3)	((			3)	((			ძ)	
(t) Terminal	mm	0.15±		0.25±0.15			0.35±0.15			0.50±0.25						±0.25		0.50±0.25				
(-)	(in.)	( , , , , , , , , , , , , , , , , , , ,		(	10±0.		(0.014±0.006)				0.020:			(0.020±0.010)				(0.020±0.010)				
	WVDC	6.3	10	6	10	16	10	16	25	50	10	16	25	50	10	16	25	50	10	16	25	50
Сар	820																					
(pF)	1000	Α	Α																			
	2200	Α	Α																			$oxed{oxed}$
	4700	Α	Α																			
Сар	0.010	Α	Α	Α	Α	Α	Α	Α	Α	Α	Υ	Υ	Υ	Υ	Z	Z	Z	Z				
(μF)	0.022	Α		Α	Α	Α	Α	Α	Α	Α	Υ	Υ	Υ	Υ	Z	Z	Z	Z				
	0.047	Α		Α	Α	Α	Α	Α	Α	Α	Υ	Υ	Υ	Υ	Z	Z	Z	Z				
	0.10	Α		Α	Α	Α	Α	Α	Α	Α	С	С	С	С	Z	Z	Z	Z	С	С	С	С
	0.22			Α	Α	Α	Α	Α	Α	Α	С	С	С	С	Z	Z	Z	Z	С	С	С	С
	0.33			Α	Α	Α	Α	Α	Α		С	С	С	С	В	В	В	В	С	С	С	С
	0.47			Α	Α	Α	Α	Α	Α		С	С	С	С	В	В	В	В	С	С	С	С
	1.0			Α	Α		Α	Α	Α		Α	Α	Α	Α	N	N	N	N	Н	Н	Н	Н
	2.2						Α	Α			Α	Α	Α		Α	Α	Α	Α	L	L	L	L
	4.7						Α				Α	Α			Α	Α	Α		L	L	L	Α
	10.0										Α				Α	Α	К		K	К	K	L
	22.0										Α				Α	Α			K	L		
	47.0																					
	WVDC	6.3	10	6	10	16	10	16	25	50	10	16	25	50	10	16	25	50	10	16	25	50
SIZE		02	01		0402			06	03		0805				1206				1210			



Case Size	0201 (KGM 03)	0402 (KGM 05)	0603 (KGM 15)	80	05 (KGM 2	.1)		120	06 (KGM	31)		1210 (KGM 32)					
Thickness Letter	Α	Α	Α	Υ	С	Α	Z	В	N	Α	K	С	Н	K	Α	L	
Max Thickness(mm)	0.33	0.55	0.90	0.76	0.95	1.45	0.76	0.94	1.27	1.80	2.29	1.27	1.80	2.29	2.70	2.80	
Carrier Tape	PAPER	PAPER	PAPER	PAPER	PAPER	EMB	PAPER	PAPER	EMB	EMB	EMB	EMB	EMB	EMB	EMB	EMB	
Packaging Code 7"reel	Н	Н	Т	T	Т	U	Т	Т	U	U	U	U	U	U	U	U	
Packaging Code 13"reel	N	N	М	М	М	L	М	М	L	L	L	L	L	L	L	L	
	PAPER			PAPER EMB			PAPER EMB				EMB						